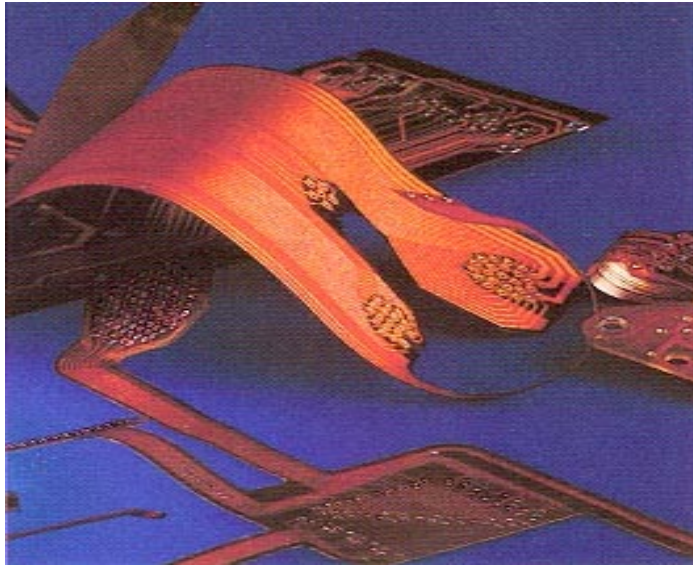




Kapton®

polyimide film

FPC-KN for Flexible Printed Circuits



Typical Properties of Kapton® FPC-KN Polyimide Film (average)

Modulus	630 kpsi
Dim. properties	CTE = 17 ppm/°C CHE = 14 ppm/% RH Shrinkage = 0.05% (200°C)
Low water absorption	2.2%
Higher productivity	fast drying time fast adhesive cure rate better stiffness for stability during processing

Kapton® Type FPC-KN

Features:

- K polymer formulation
- High modulus
- Tailored dimensional properties (thermal expansion matched to copper)
- Fast drying rate
- Fast adhesive cure time

Available:

- 100FPC-KN
- 200FPC-KN
- 300FPC-KN

Applications:

- Roll clads
- Flexible printed circuits requiring better dimensional stability

United States (800) 967-5607 – Canada (800) 784-5231 – Europe 352-3666-4004
 Japan 81-3-5434-6139 - DuPont Toray Co. 81-3-3245-5061 – Hong Kong 852-2734-5461
 China/Beijing 86-10-65227010 - India 91-22-8390770 – Korea 82-2-222-5399
 Singapore 65-279-3527 - Taiwan 886-3-3773604